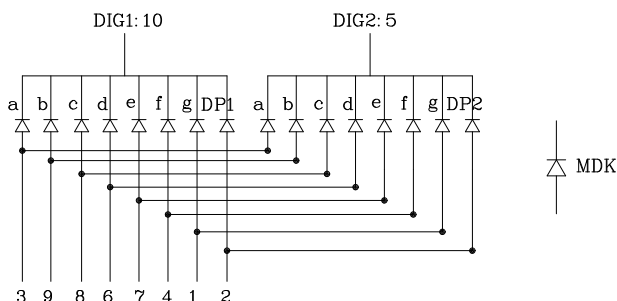


PRELIMINARY SPEC

Features

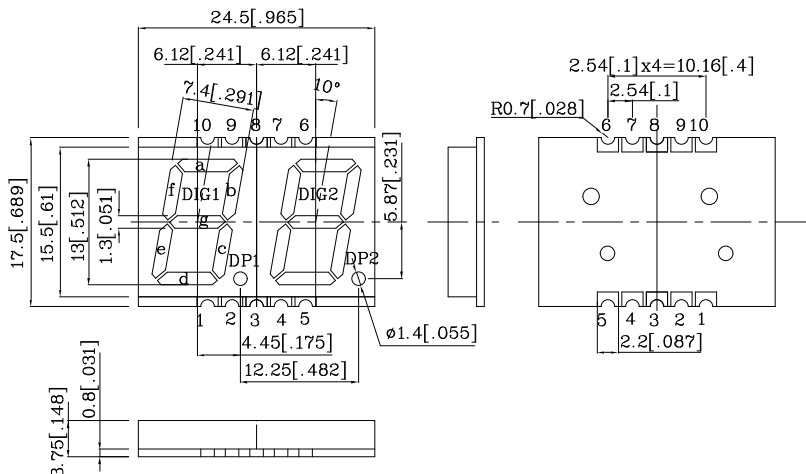
- 0.51 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE,WHITE SEGMENT.
- PACKAGE : 200PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



Notes:

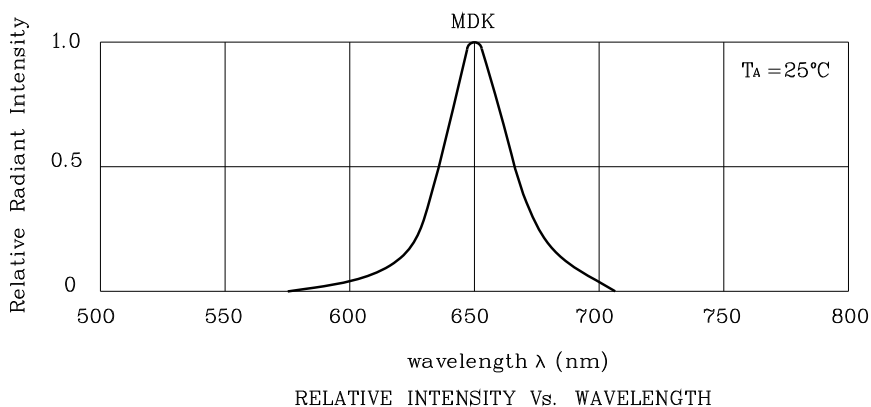
1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. The gap between the reflector and PCB shall not exceed 0.25mm.
- 4.Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)		MDK (InGaAlP)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	185	mA
Power Dissipation	P _T	75	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	

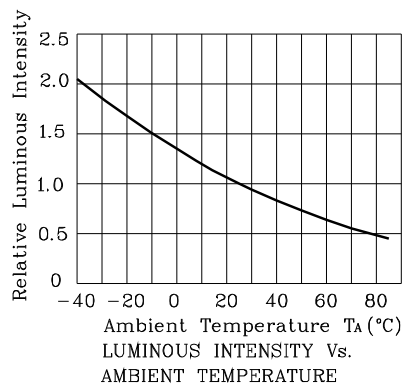
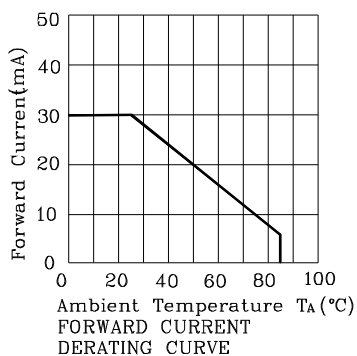
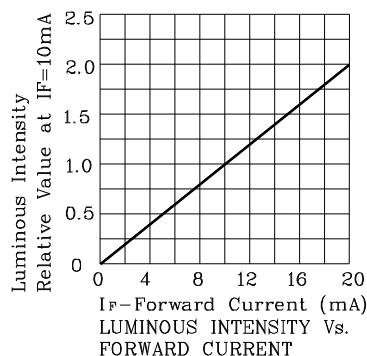
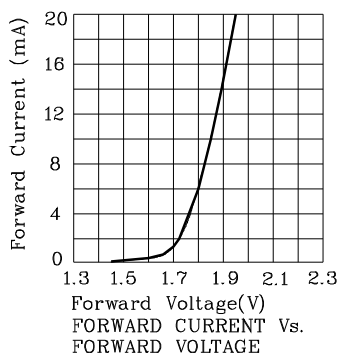


Operating Characteristics (TA=25°C)		MDK (InGaAlP)	Unit
Forward Voltage (Typ.) (IF=10mA)	V _F	1.85	V
Forward Voltage (Max.) (IF=10mA)	V _F	2.5	V
Reverse Current (Max.) (VR=5V)	I _R	10	uA
Wavelength of Peak Emission (Typ.) (IF=10mA)	λ P	650	nm
Wavelength of Dominant Emission (Typ.) (IF=10mA)	λ D	635	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=10mA)	Δλ	28	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	35	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd	Wavelength nm λ P	Description	
			min.	typ.		
ZFMDK129C2	Red	InGaAlP	12000	41040	650	Common Cathode. Rt. Hand Decimal
Published Date : FEB 28, 2008		Drawing No : SDSA6474		V1	Checked : Shin Chi	P.1/4



❖ MDK



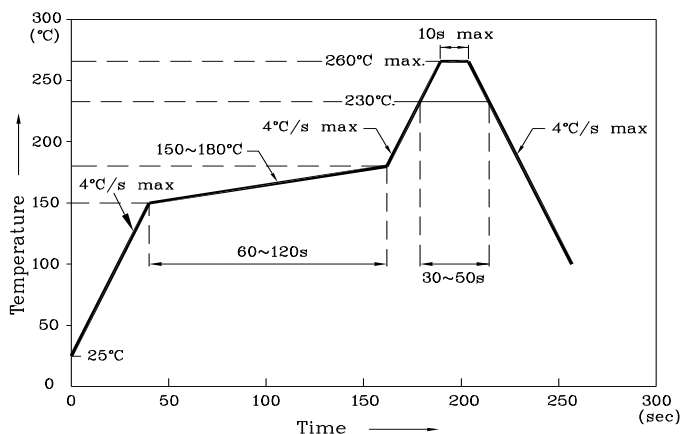
Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: $\pm 1\text{nm}$
2. Luminous Intensity / Luminous Flux: $\pm 15\%$
3. Forward Voltage: $\pm 0.1\text{V}$

Note: Accuracy may depend on the sorting parameters.

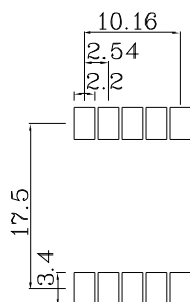
Reflow Soldering Profile For Lead-free SMT Process.



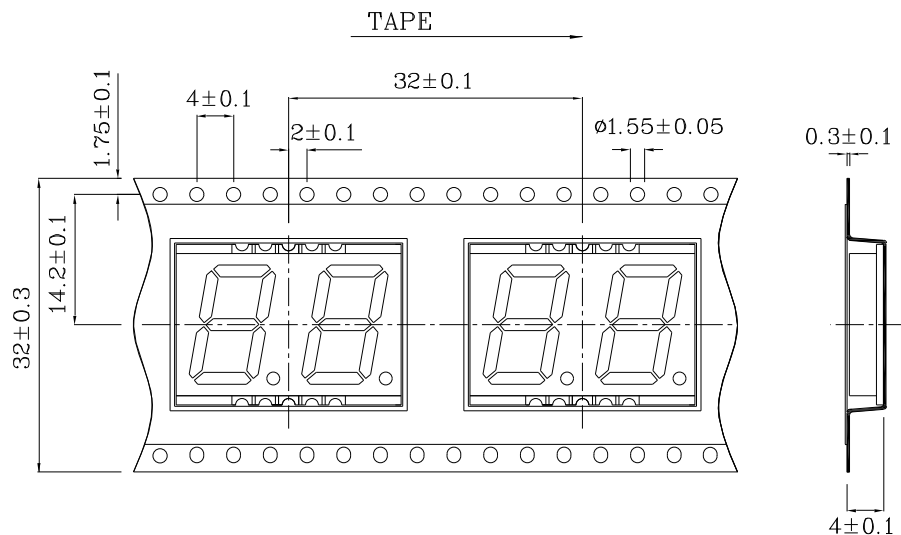
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance:± 0.15)



❖ Tape Specification (Units : mm)



PACKING & LABEL SPECIFICATIONS

ZFMDK129C2

